

EV317135795

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Priority Application Serial No. .... 10/039,456  
Priority Filing Date .... December 31, 2001  
Inventor .... Ying Huang et al.  
Assignee .... Micron Technology, Inc.  
Priority Group Art Unit .... 2829  
Priority Examiner .... S.B. Geyer  
Attorney's Docket No. .... MI22-2347  
TITLE: An Improved Method, Structure and Process Flow to Reduce Line-Line  
Capacitance with Low-K Material

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Commissioner for Patents  
Alexandria, VA 22313-1450

Attention: Official Draftsman


**SUBSTITUTE DRAWING REQUEST**

Please enter the enclosed substitute drawings in the above-referenced application in place of drawings originally filed. The content of the drawings are identical to those now on file in this application.

Acknowledgment of receipt of the formal drawings and their acceptance into the file is requested.

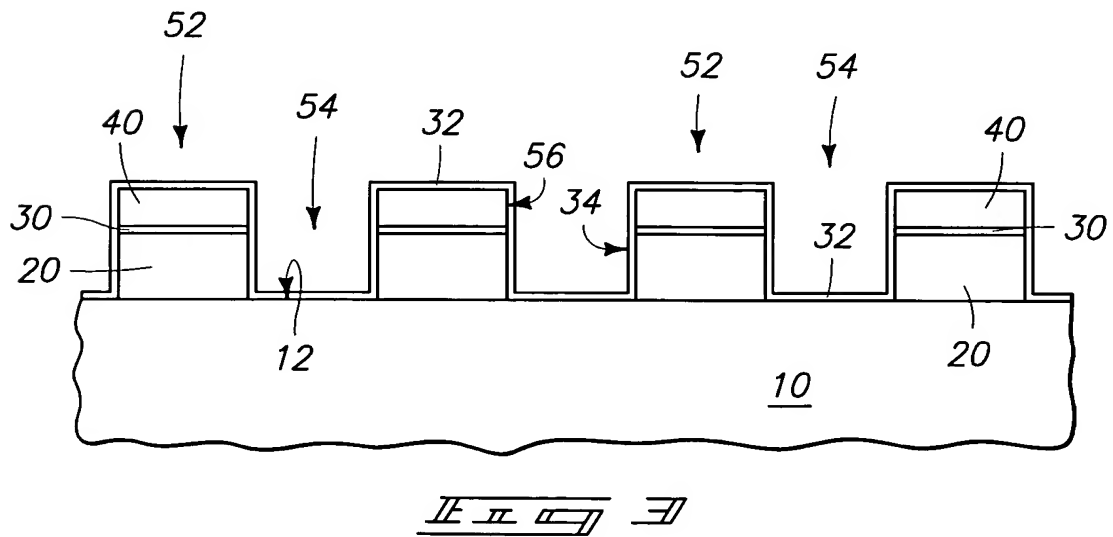
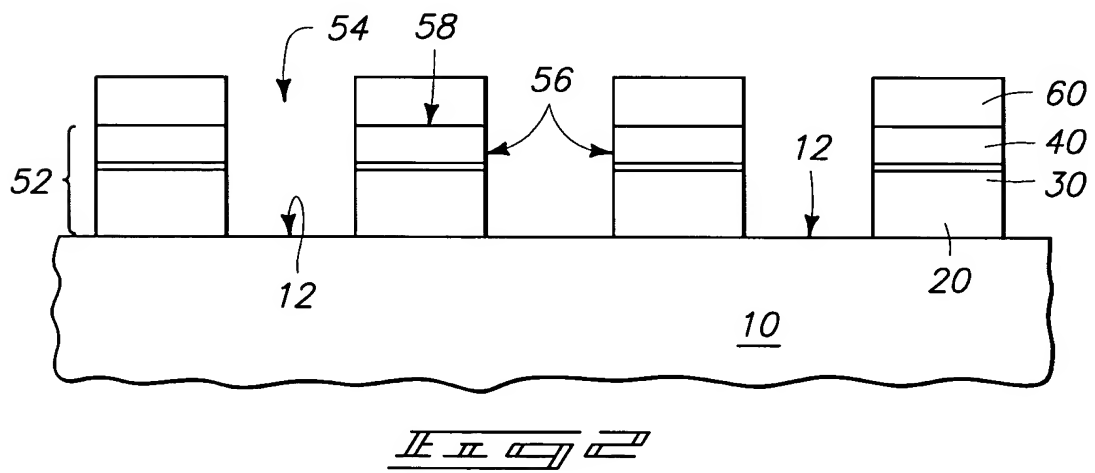
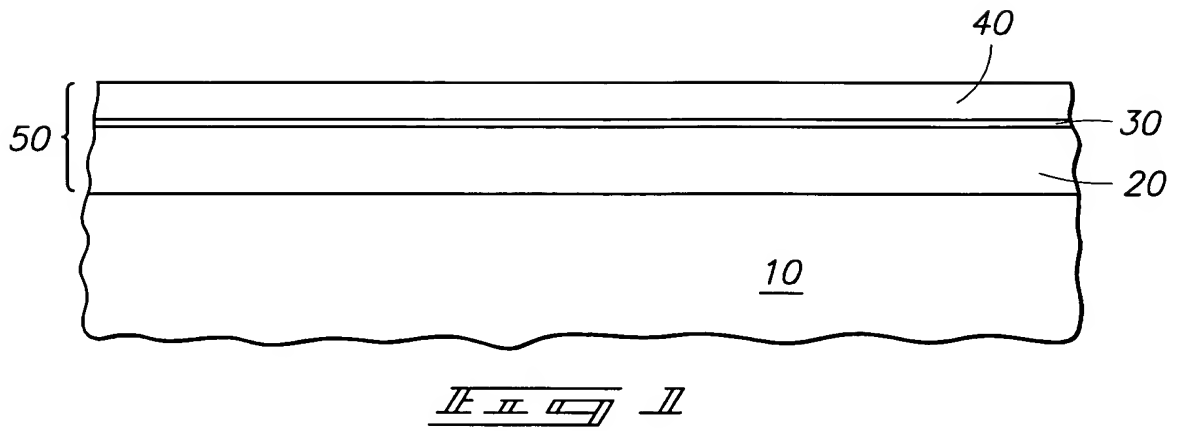
Respectfully submitted,

Date: 7-23-03

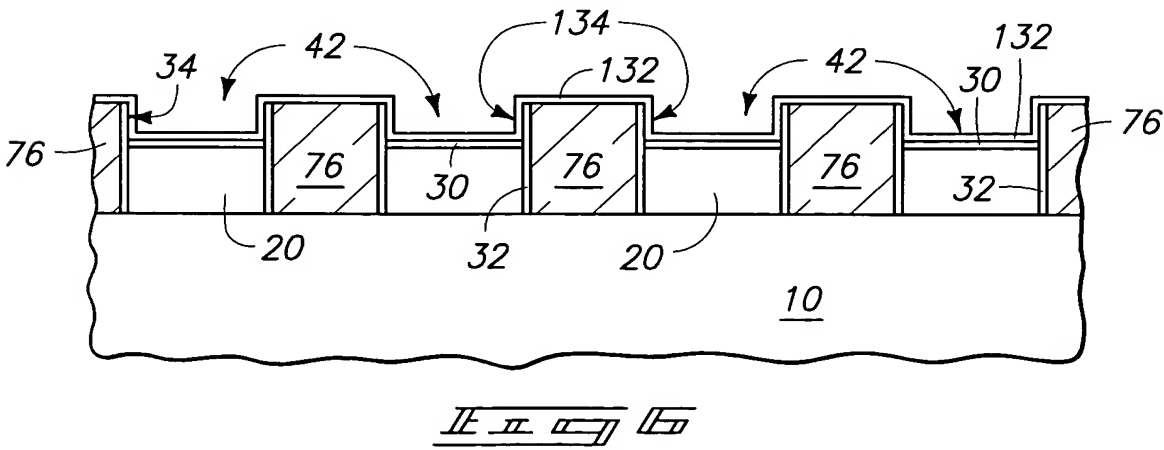
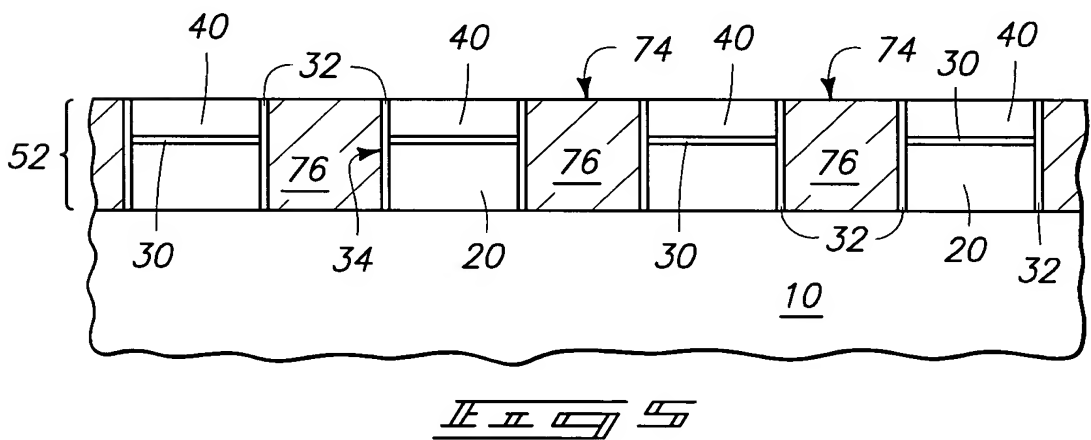
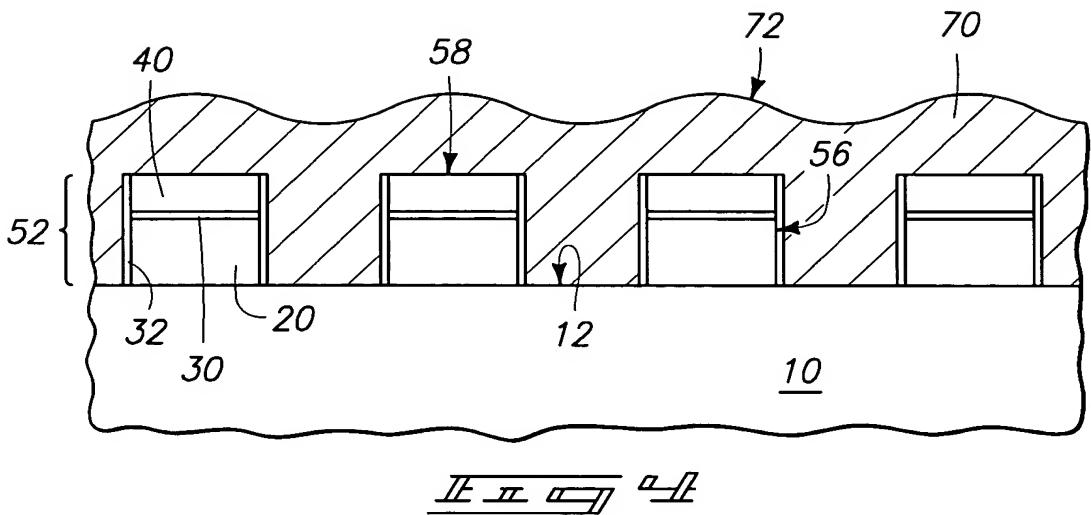
By:   
D. Brent Kenady  
Reg. No.: 40,045  
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601 W. First Avenue, Suite 1300  
Spokane, WA 99201-3828  
(509) 624-4276

Enclosures: 5 Sheets of Formal Drawings, Figs. 1-14.

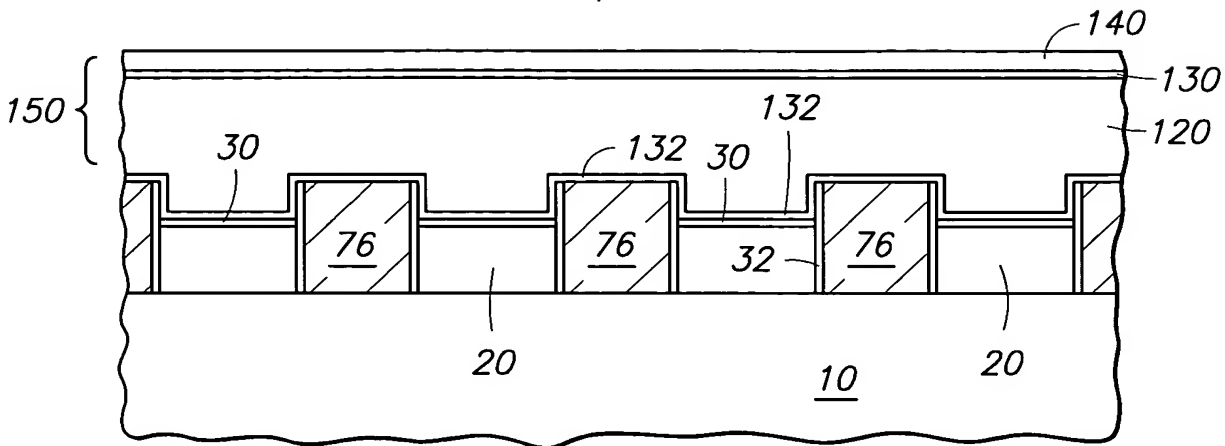
1/5



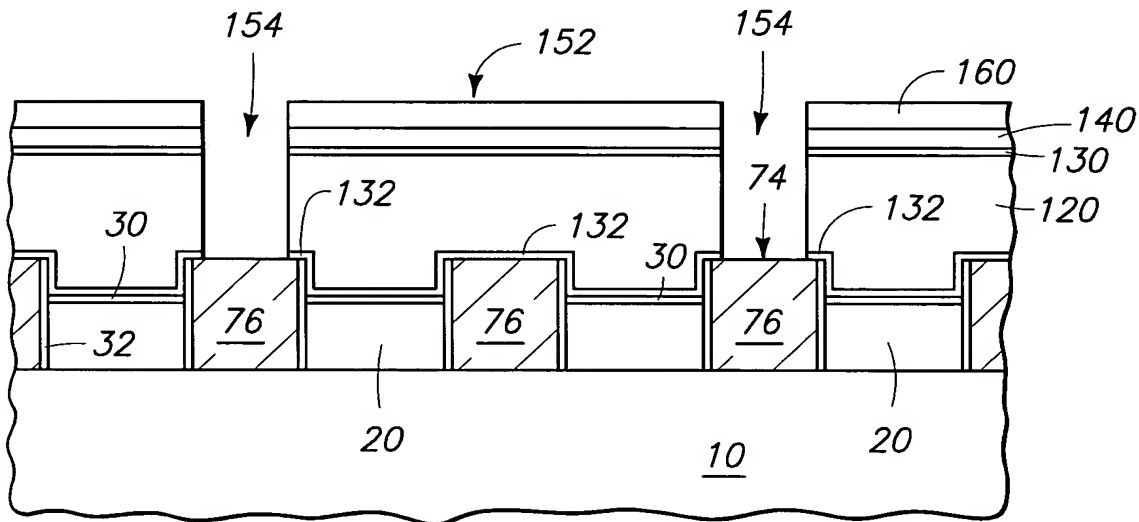
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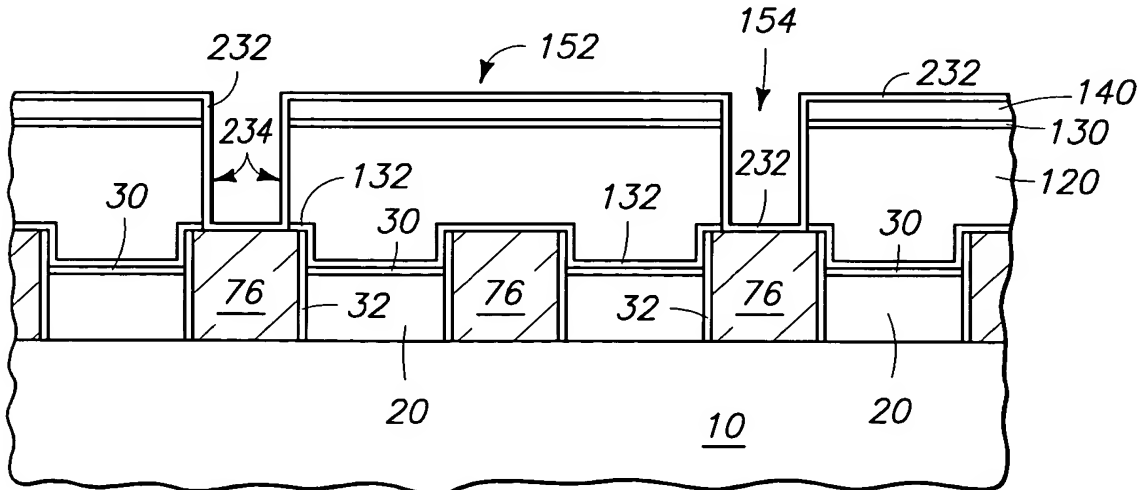
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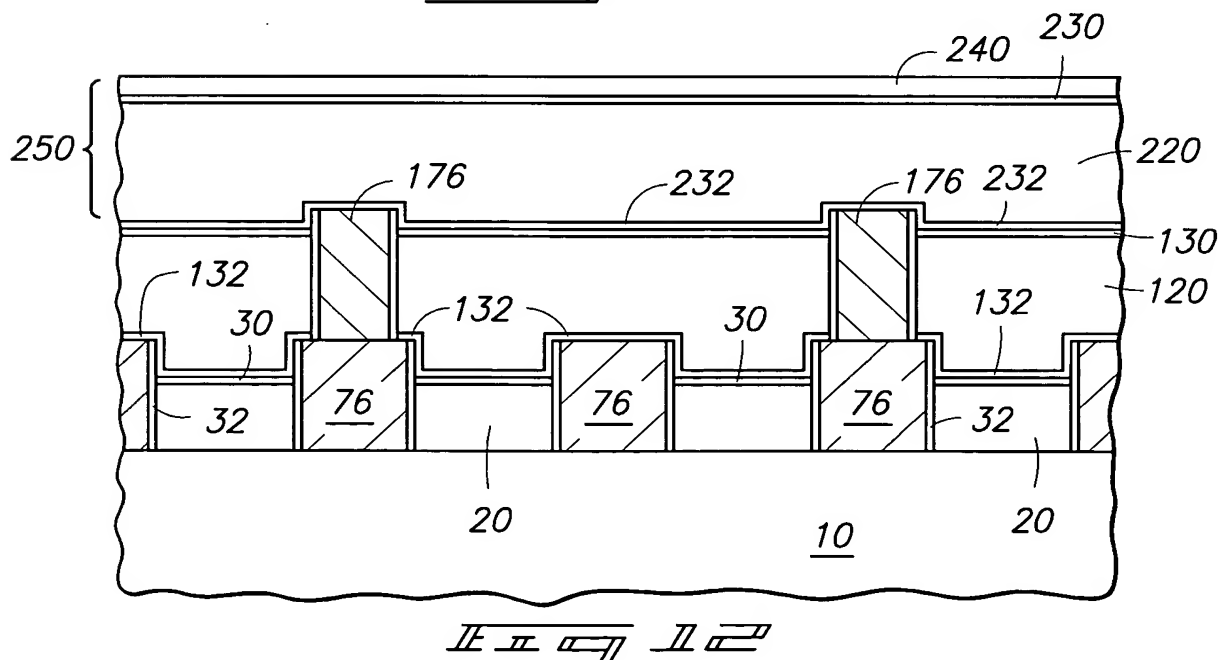
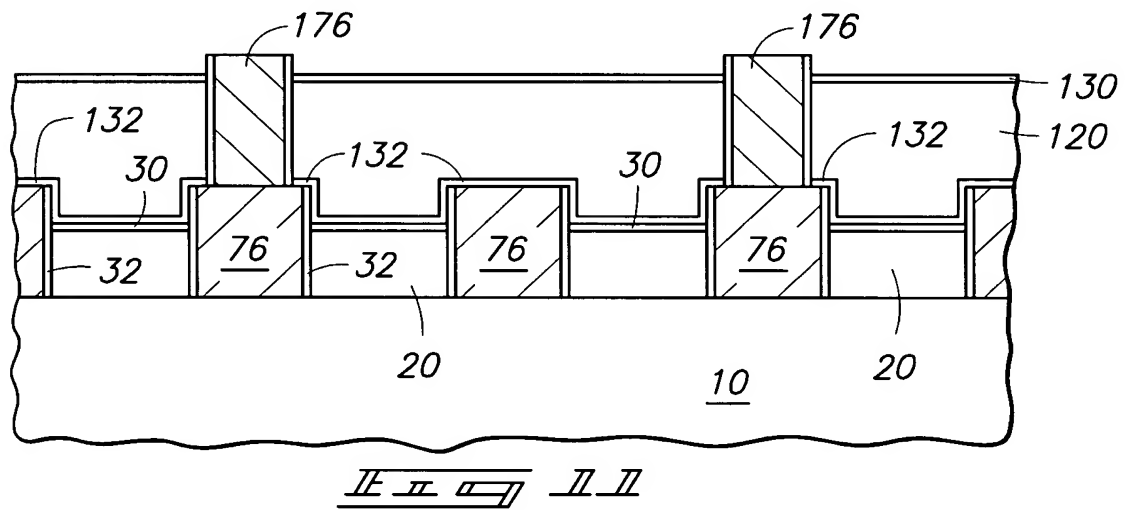
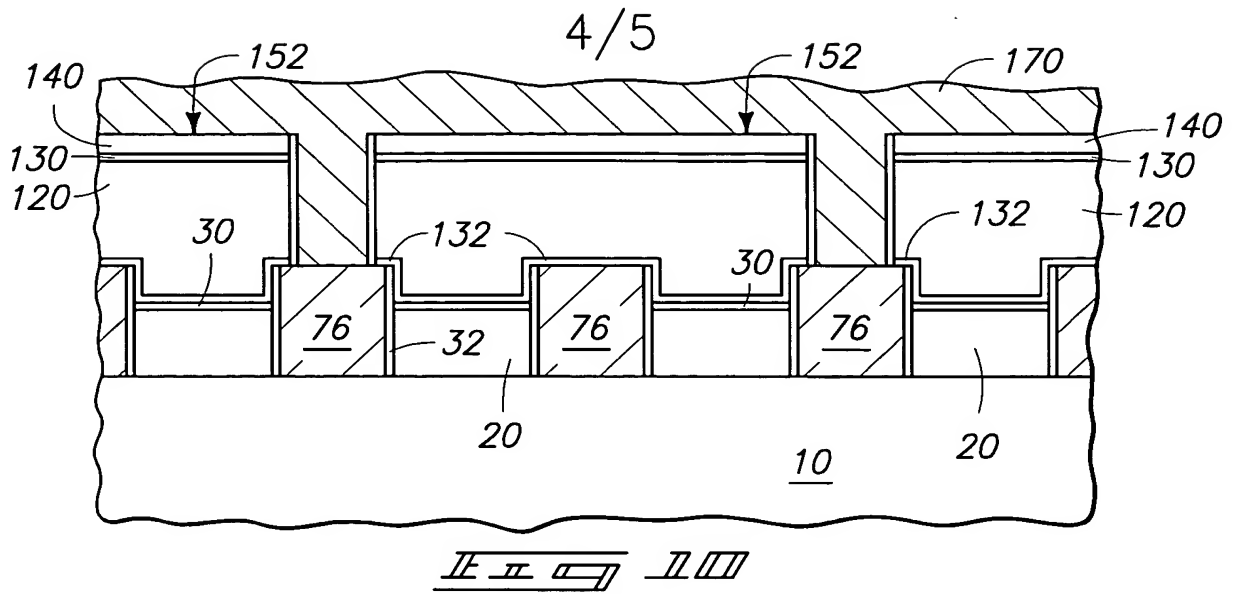
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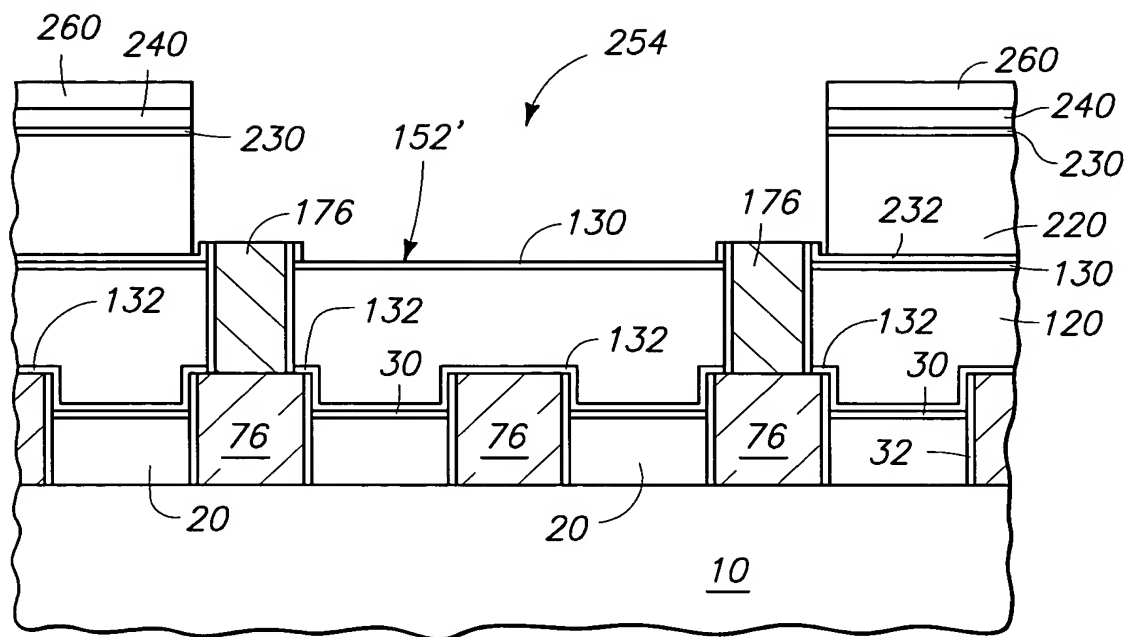
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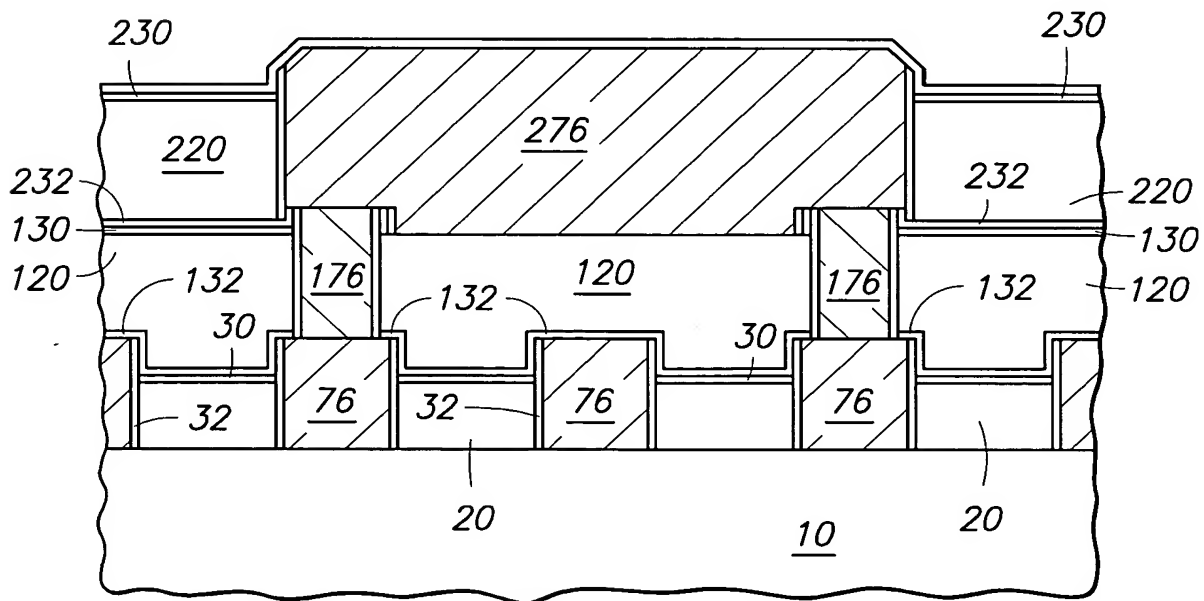
II-II



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